

Symposium on Advanced Packaging and Heterogeneous Integration Driving Embedded System Innovation

Call for Papers and Presentations

I. Conference Background

Embedded World ranks among the world's most authoritative professional platforms for embedded systems, featuring cutting-edge technology demonstrations, in-depth technical exchanges and global industrial collaboration. The exhibition fully showcases the complete embedded ecosystem — ranging from basic electronic components and functional modules, core operating systems, hardware and software design, to M2M communication and complex system integration — covering all links along the industrial value chain. Its conference agenda consistently focuses on hot technical topics including artificial intelligence, edge computing and cybersecurity. Adhering to the core tenet of "by engineers, for engineers", it delivers forward-looking technical outlooks and actionable practical insights for embedded developers and industrial decision-makers across the globe.

Drawing on Embedded World's global vision and profound industry expertise, this Symposium echoes the core positioning of the China Semiconductor Expo — "Chip-Connected Industry, Smart Creating the Future" — and leverages its full-industry-chain platform advantages covering chip R&D, manufacturing, packaging & testing, equipment and materials, and industrial terminal applications. In the post-Moore era, embedded systems can no longer satisfy stringent requirements for high performance, low power consumption and miniaturization merely through process shrinking. Advanced packaging and heterogeneous integration have become key enablers to overcome performance bottlenecks. Meanwhile, the rapid expansion of embedded AI and booming ecosystem of the open RISC-V architecture bring new opportunities and challenges to full-industry chain collaborative innovation covering chip design, packaging integration and system-level applications.

The symposium is designed to bridge the closed technology loop covering manufacturing processes, packaging integration and embedded applications. It will focus on core themes including high performance chip fabrication for industrial-grade embedded AI, customized computing acceleration based on RISC-V, System-in-Package (SiP) and 2.5D/3D heterogeneous integration technologies, as well as real-world deployments of machine vision for advanced packaging inspection and embedded systems. We will gather leading enterprises spanning chip design, packaging & testing, EDA tools, system integration and complete machine manufacturing to discuss how application demands drive semiconductor technological innovation and accelerate the efficient industrial implementation of chips in end devices.

This event not only inherits and deepens Embedded World's "by engineers, for engineers" philosophy, but also fully embodies the full-chain value proposition of the China Semiconductor Expo — "From Chips to Scenarios". It returns technology to the core venue of industrial applications and enables innovations to grow from authentic industrial demands.

II. Proposed Topics (non-exhaustive)

- High-performance chip manufacturing processes for embedded AI;
- RISC-V architecture-based AI computing solutions for embedded systems;
- Advanced packaging applications in embedded AI and automotive electronics;
- 2.5D/3D EDA tools and STCO co-design methodologies;
- SiP system-in-package enabling miniaturization and modular design for embedded terminals;
- Chip-level hardware/software co-solutions for embedded machine vision;
- Architecture challenges and deployment case studies of high-performance embedded systems in industrial vision and AI-driven quality inspection;
- Vision inspection challenges in advanced packaging processes and intelligent AOI technical solutions;
- Packaging reliability and system integration for automotive-grade embedded chips;
- Innovative applications of embedded vision in embodied intelligence and smart terminals.

III. Target Audience for Submissions / Participants

- Semiconductor Design & Packaging Engineers
- Embedded System Engineers & Hardware Architects
- System Integrators and Module Manufacturers
- Researchers from Academic Institutions and Universities

IV. Submission Content Requirements

(I) Required Submission Materials (Bilingual in Chinese and English, Mandatory)

1. Presentation Title (in both Chinese and English)
2. Presentation Abstract: approximately 500 words in Chinese, approximately 1,500 characters in English
3. Speaker Information: name, company/academic institution and title/position, mobile phone number, email address
4. Speaker Biography: approximately 500 words in Chinese, approximately 1,500 characters in English

(II) Selection Criteria for Submissions

1. Selection Criteria: Submissions must be authentic, original, and offer innovative perspectives. Preference is given to real projects that the submitter has personally worked on.
2. Exclusive Submission: Submissions must not have been previously published in other journals, conferences, or proceedings. Simultaneous submission to multiple outlets is not permitted.
3. No Marketing Content: The organizers do not accept marketing-oriented submissions or content that is purely product-descriptive.
4. Language: Bilingual in Chinese and English. Please provide presentation materials in both Chinese and English versions.

V. Key Milestones

1. Presentation Abstract Submission Deadline: September 4, 2026
2. Official Conference Agenda Announcement: September 30, 2026
3. Final Presentation PPT and Complete Presentation Materials Submission Deadline: September 23, 2026

VI. Submission Guidelines

1. This seminar is open to technical presentation submissions from the entire industry chain. Outstanding submissions will be arranged for on-site featured presentations.
2. All submissions will be reviewed by the organizing committee's technical experts. Selected speakers and the full agenda will be publicly announced before September 30.
3. Submission materials should be compiled into bilingual documents and sent to the organizing committee's submission inquiry email address: event@luminlinkpr.com
4. For questions regarding topic directions or material formatting, please contact the organizing committee via "RPC Forwarding Inquiry" for assistance.

VII. Conference Value

1. Premier Industry Exchange Platform: Leveraging the international resources of Embedded World, connecting with global embedded systems and semiconductor upstream and downstream enterprises.
2. Precise Matchmaking Across the Entire Industry Chain: Covering professional audiences in chips, packaging and testing, EDA, embedded hardware, industrial vision, automotive electronics, and AI terminals.
3. Public Sharing of Technical Advancements: Delivering technical solutions to engineers, helping enterprises and research institutions build their technology brand.
4. Industry-Commercialization Resource Integration: Directly engaging with end-device manufacturers and system integrators to establish cooperation channels for the commercialization of technical achievements.

演讲资料征集表
Speech sponsor - Registration Form

演讲题目： (必填)

Title of the Presentation: (Required)

演讲摘要 (约 500 字): (必填)

Presentation abstract (about 1500 words) : (Required)

(必填)

演讲人姓名：

职务：

移动电话：

电子邮箱：

演讲人简介 (约 500 字)：

(Required)

Speaker' s Name:

Job Title:

Mobile Phone:

E-mail:

Speaker biography (about 1500 words) :

PS:

温馨提示: 准备以上内容时, 请不要忽略以下内容:

Please Note: The following points should not be overlooked when preparing the above materials:

- **入选标准** - 真实、原创、具有创新视角, 尽量是投稿人亲自做过的真实项目。
 - **独家投稿** - 要求投稿内容未在其他期刊、会议或论文集中发表过, 请勿一稿多投。
 - **谢绝营销** - 主办方不接受以营销为导向以及单纯产品描述的投稿内容。
 - **资料语言** - 中英文双语对照。请提供演讲资料的中、英文双语版本。
- **Selection Criteria** – Submissions must be authentic, original, and offer innovative perspectives. Preference is given to real projects that the submitter has personally worked on.
- **Exclusive Submission** – Submissions must not have been previously published in other journals, conferences, or proceedings. Simultaneous submission to multiple outlets is not permitted.
- **No Marketing Content** – The organizers do not accept marketing-oriented submissions or content that is purely product-descriptive.
- **Language** – Bilingual in Chinese and English. Please provide presentation materials in both Chinese and English versions.

请留意以下重要日期

Please take note of the following key dates:

摘要提交: 2026 年 9 月 4 日前截止

Abstract Submission: Due by September 4, 2026

议程公布: 2026 年 9 月 30 日

Agenda Publication: September 30, 2026

最终资料及演讲材料定稿: 2026 年 9 月 23 日

Final Presentation Materials Submission: September 23, 2026